### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4819529

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Wen-Kai Lin	02/08/2018
Yi-Chung Sheng	02/08/2018
Sheng-Yuan Hsueh	02/08/2018
Chih-Kai Kang	02/08/2018

#### **RECEIVING PARTY DATA**

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Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	15893709

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	NAUP3225USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	02/12/2018

#### **Total Attachments: 8**

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PATENT 504772801 REEL: 044890 FRAME: 0736



PATENT REEL: 044890 FRAME: 0737

#### Title of Invention:

### SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:		
The attached application, or	r		
☐ United States application nu	ımber	_filed on, or	
☐ PCT international applicatio	n number	filed on	
The above-identified application was	made or authorized to be made	by me.	-
I believe that I am the original invent application.	or or an original joint inventor of a	claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this decisionment of not more than five (5)	laration is punishable ) years, or both.	
In consideration of the payment by	UNITED MICROELECTRON	IICS having a postal address	s of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, Hsi	n-Chu City 300, Taiwan, R.	.o.c.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1.0 and valuable consideration.	0), the receipt of which is hereby	/
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat r any continuations, continuation-i	hich are disclosed in the ent to be obtained for said n-part, divisions, renewals	
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbran n this assignment;	ce has been or will be made or	
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and I stify as to the same in any interfe	egal equivalents as may be rence, litigation proceeding	
representatives any and all papers, in maintain, issue and enforce said appequivalents thereof which may be nearly WITNESS WHEREOF, I have her	dication, said invention and said Lacessary or desirable to carry out t	etters Patent and said	ing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including r s form. Use this form for <u>each ado</u>	naming the entire litional inventor.	

Page 1 of 8

NPO#NAU-P3225-USA:0 CUST#UMCD-2017-0697

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Wen-Kai Lin		Date:	FEB 0 8 2018'	
Signature:	Wen-Kai	Lin			_

Page 2 of 8

NPO#NAU-P3225-USA:0 CUST#UMCD-2017-0697

#### Title of Invention:

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hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w ation and, in and to, all Letters Pat r any continuations, continuation-	hich are disclosed in the tent to be obtained for said in-part, divisions, renewals.	EE
hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbran h this assignment;	nce has been or will be made	or
further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents as may be erence, litigation proceeding	ts
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne N WITNESS WHEREOF, I have he	olication, said invention and said tecessary or desirable to carry out	Letters Patent and said	signing)
Note: An application data sheet (PT0 nventive entity, must accompany thi	O/SB/14 or equivalent), including is form. Use this form for <u>each ad</u>	naming the entire ditional inventor.	

Page 3 of 8

#### Docket No NAUP3225USA

	Yi-Chung Sheng		Date:	FEB 0 8 2018	
Signature:	Yi- Chung	Sheng			

LEGAL NAME OF INVENTOR/ACCIONODY

Page 4 of 8

NPO#NAU-P3225-USA:0 CUST#UMCD-2017-0697

## Title of Invention: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Do nd valuable consideration	llar (\$ 1.00), the เ า.	receipt of which	is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improve ition and, in and to, all Le r any continuations, cont	ements which are etters Patent to be tinuation-in-part, o	disclosed in the e obtained for s divisions, renew	e aid ⁄als,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or er h this assignment;	ncumbrance has	been or will be r	made or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will terelated thereto and will promptly exe	ntion and said Letters Pa estify as to the same in a	itent and legal eq iny interference, l	uivalents as ma itigation proceed	ly be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention a ecessary or desirable to	and said Letters F carry out the prop	Patent and said poses thereof.	ate of signing)
Note: An application data sheet (PT0 inventive entity, must accompany thi				

Page 5 of 8

#### Docket No NAUP3225USA

LEGAL NAM	ME OF INVENTOR(ASSIGNOR)					
Inventor:	Sheng-Yuan Hsueh	Date:	FEB	0 8	2018	
Signature:	Sheng-Tuan	(-sue	h			

Page 6 of 8

#### Title of Invention:

#### SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, an	nd to any and all improvem ition and, in and to, all Lette r any continuations, continu	ents which are ers Patent to b uation-in-part, o	e disclosed in the e obtained for said divisions, renewals	,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encu h this assignment;	ımbrance has	been or will be mad	de or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exe	ntion and said Letters Pater estify as to the same in any	nt and legal eq interference, l	uivalents as may bitigation proceeding	е
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention and ecessary or desirable to car	said Letters F ry out the prop	Patent and said poses thereof.	of signing)
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Page 7 of 8

NPO#NAU-P3225-USA:0 CUST#UMCD-2017-0697

#### Docket No NAUP3225USA

LEGAL NAME OF INVENTOR(ASSIGNOR)			
Inventor:	Chih-Kai Kang	Date:	FEB 0 8 2018
Signature:	Chih-kai ka	mg	

NPO#NAU-P3225-USA:0 CUST#UMCD-2017-0697

**RECORDED: 02/12/2018** 

Page 8 of 8

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PATENT REEL: 044890 FRAME: 0745